



245 No-Clean Cored Wire for Lead-Free and Leaded Alloys

Product Description

Kester 245 was developed to complement low residue liquid fluxes being used by the electronics industry. The chemistry is based on some of the same principles that have been safely used for years in mildly activated rosin fluxes. The use of 245 results in visually acceptable assemblies without cleaning, yet soldering quality and efficiency is comparable to that obtained with mildly activated rosin flux. 245 was formerly classified as Type LR per MIL-F-14256. 245 is Bellcore GR-78 compliant.

Performance Characteristics:

- Highly reliable post-soldering residue
- Minimal residue
- Compatible with leaded and lead free alloys
- Classified as ROL0 per J-STD-004
- Compliant to Bellcore GR-78

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2011/65/EU for the stated banned substances. (Applies only if this core flux is combined with a lead-free alloy)

Reliability Properties

Copper Mirror Corrosion: Low
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Chloride and Bromides: None Detected
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Spread Test (typical):
Tested to J-STD-004, IPC-TM-650, Method 2.4.46

	Area of Spread (in ²) mm ²
Flux Core Solder	Sn63Pb37
Plastic Rosin Core	194 (0.30)
285 Mildly Activated Rosin	335 (0.52)
245 No-Clean	348 (0.54)

Silver Chromate: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Surface Insulation Resistivity (SIR), IPC (typical): Pass
Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	245
Day 1	1.2*10 ¹⁰ Ω	1.7*10 ⁹ Ω
Day 4	9.4*10 ⁹ Ω	1.9*10 ⁹ Ω
Day 7	8.6*10 ⁹ Ω	2.1*10 ⁹ Ω

Surface Insulation Resistivity (SIR) 40C/90%RH, IPC (typical): Pass
Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7

Availability

245 cored wire is available in a wide variety of alloys, wire diameters, flux percentages and roll sizes in both leaded and lead free alloys. Please refer to www.kester.com for wire diameters, flux percentages and roll sizes that are available.

Note: Core size 50, 58 and 66 = 1.1%, 2.2% and 3.3% flux core.

Process Considerations

Solder iron tip temperatures are most commonly between 315-343°C (600-650°F) for Sn63Pb37 and Sn62Pb36Ag02 alloys, and 371-400°C (700-750°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to touching the land with the cored wire. Do not apply the wire directly to the soldering iron tip. If needed, Kester 951 or 952-D6 no clean flux may be used as a compatible liquid flux to aid in reworking soldered joints. Kester 951 and 952-D6 are available in Flux-Pens[®] for optimum board cleanliness.

Cleaning

The 245 flux residues are non-corrosive, non-conductive and do not require removal in most applications. IPA will not clean the residues off the surface of the circuit board after the soldering process. A saponifier or cleaning agent specifically designed to clean a no-clean flux is required to clean the residues. Please contact Kester Technical Support for further information.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet (SDS) and warning label before using this product.

Storage and Shelf Life

Storage must be in a dry, non-corrosive environment. The surface may lose its shine and appear a dull shade of gray. This is a surface phenomena and is not detrimental to product functionality. Flux cored solder wire has a limited shelf life determined by the alloy used in the wire. For alloys containing more than 70% lead, the shelf life is two years from the date of manufacture. Other alloys have a shelf life of three years from date of manufacture.